

BondMachine, a mouldable computer architecture



an OS-less approach to reduce the Software/Hardware gap

The BondMachine (BM) is an innovative computer architecture built on two main components: Connecting Processors (CPs) and Shared Objects (SOs). CPs have different Instruction Set Architecture (ISA) and can be connected together sharing resources. The result is a heterogeneous system perfectly fitted to a specific computational problem. The cores are particularly simple (i.e. optimized to execute atomic tasks), and their problem solving potential mainly relies on how they are interconnected. Moreover, in order to use many well-known tools and techniques ranging from languages to compilers, the "register machine" abstraction has been kept.

The BM can be used as a general purpose computer architecture or as an high specialized device perfectly suited to fit specific problems; furthermore the BM is flexible enough to be adopted in different scenarios like Internet of Things (IoT), Cyber Physical System (CPS) and High Performance Computing (HPC).

The flexibility of the BM architecture makes possible the use of evolutionary algorithms that select architectures, processors programs and interconnections.

Currently the BM is implemented by using the Field Programmable Gate Array (FPGA) chips that are the most powerful implementations of reconfigurable hardware nowadays. The implemented EtherBond protocol allows to build distributed systems.

The BM architecture combined with all these technologies results in a brand new computing environment: **The BondMachine Ecosystem**.

